

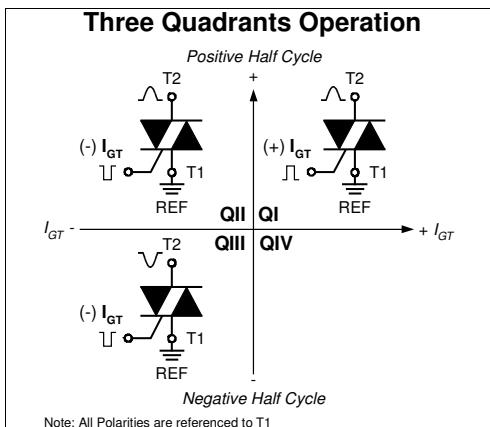
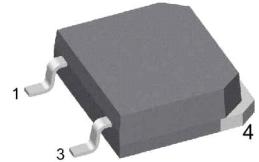
# High Efficiency Thyristor

$V_{RRM}$  = 1200 V  
 $I_{TAV}$  = 30 A  
 $V_T$  = 1,25 V

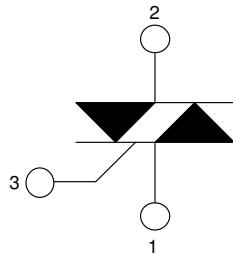
Three Quadrants operation: QI - QIII  
1~ Triac

## Part number

**CLA60MT1200NTZ**



Backside: anode/cathode



## Features / Advantages:

- Triac for line frequency
- Three Quadrants Operation - QI - QIII
- Planar passivated chip
- Long-term stability of blocking currents and voltages

## Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

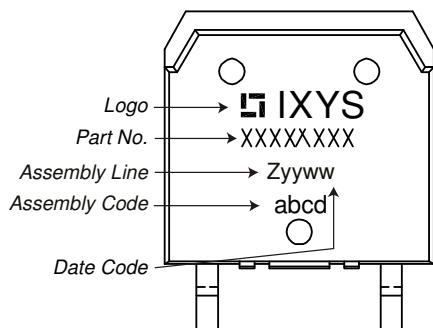
## Package: TO-268AA (D3Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- High creepage distance between terminals

Rectifier			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1300	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1200	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1200 V$ $V_{R/D} = 1200 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		10 2	$\mu A$ mA
$V_T$	forward voltage drop	$I_T = 30 A$ $I_T = 60 A$ $I_T = 30 A$ $I_T = 60 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		1,28 1,56 1,25 1,61	V V V V
$I_{TAV}$	average forward current	$T_C = 120^\circ C$	$T_{VJ} = 150^\circ C$		30	A
$I_{RMS}$	RMS forward current per phase	180° sine			66	A
$V_{TO}$	threshold voltage	$r_T$ slope resistance } for power loss calculation only	$T_{VJ} = 150^\circ C$		0,86	V
	slope resistance				12,5	$m\Omega$
$R_{thJC}$	thermal resistance junction to case				0,55	K/W
$R_{thCH}$	thermal resistance case to heatsink				0,15	K/W
$P_{tot}$	total power dissipation		$T_C = 25^\circ C$		220	W
$I_{TSM}$	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$		380 410 325 350	A A
$I^2t$	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$		720 700 530 510	$A^2s$ $A^2s$ $A^2s$ $A^2s$
$C_J$	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$		25	pF
$P_{GM}$	max. gate power dissipation	$t_p = 30 \mu s$ $t_p = 300 \mu s$	$T_C = 150^\circ C$		10 5 0,5	W W W
$P_{GAV}$	average gate power dissipation					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^\circ C; f = 50 \text{ Hz}$ repetitive, $I_T = 90 A$ $t_p = 200 \mu s; di_G/dt = 0,3 A/\mu s;$ $I_G = 0,3 A; V = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 30 A$			150	$A/\mu s$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$ ; method 1 (linear voltage rise)	$T_{VJ} = 150^\circ C$		500	$V/\mu s$
$V_{GT}$	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$		1,7 1,9	V V
$I_{GT}$	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$		$\pm 60$ $\pm 80$	mA mA
$V_{GD}$	gate non-trigger voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^\circ C$		0,2	V
$I_{GD}$	gate non-trigger current				$\pm 1$	mA
$I_L$	latching current	$t_p = 10 \mu s$ $I_G = 0,3 A; di_G/dt = 0,3 A/\mu s$	$T_{VJ} = 25^\circ C$		90	mA
$I$	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		60	mA
$t_{gd}$	gate controlled delay time	$V = \frac{1}{2} V_{DRM}$ $I_G = 0,3 A; di_G/dt = 0,3 A/\mu s$	$T_{VJ} = 25^\circ C$		2	$\mu s$
$t_q$	turn-off time	$V = 100 V; I_T = 30 A; V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 150^\circ C$ $di/dt = 10 A/\mu s$ $dv/dt = 20 V/\mu s$ $t_p = 200 \mu s$			150	$\mu s$

**Package TO-268AA (D3Pak-HV)**

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
$I_{RMS}$	$RMS$ current	per terminal			70 A
$T_{VJ}$	virtual junction temperature		-40		150 °C
$T_{op}$	operation temperature		-40		125 °C
$T_{stg}$	storage temperature		-40		150 °C
<b>Weight</b>				4 g	
$F_c$	mounting force with clip		20		120 N
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	9,4		mm
$d_{Spb/Apb}$		terminal to backside	5,6		mm

**Product Marking****Part description**

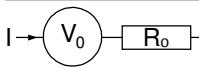
C = Thyristor (SCR)  
 L = High Efficiency Thyristor  
 A = (up to 1200V)  
 60 = Current Rating [A]  
 MT = 1~ Triac  
 1200 = Reverse Voltage [V]  
 N = Three Quadrants operation: QI - QIII  
 TZ = TO-268AA (D3Pak) (2HV)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLA60MT1200NTZ	CLA60MT1200NTZ	Tube	30	512767

Similar Part	Package	Voltage class
CLA60MT1200NHB	TO-247AD (3)	1200
CLA60MT1200NHR	ISO247 (3)	1200

**Equivalent Circuits for Simulation**

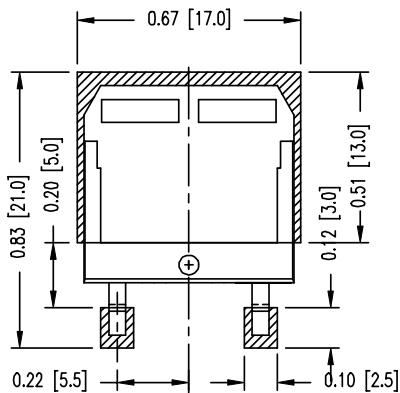
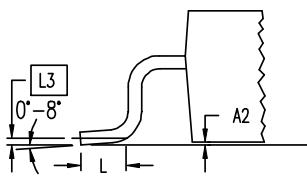
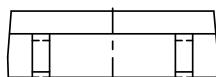
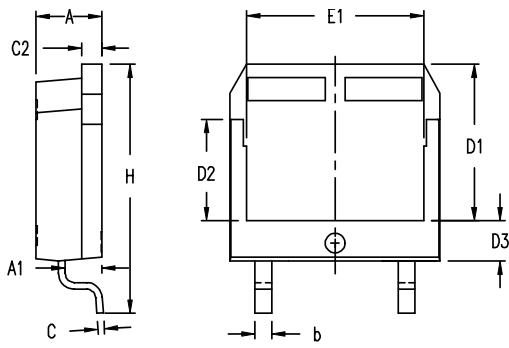
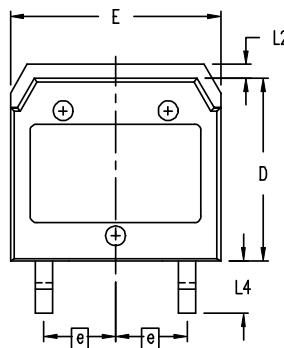
\* on die level

 $T_{VJ} = 150$  °C

Thyristor

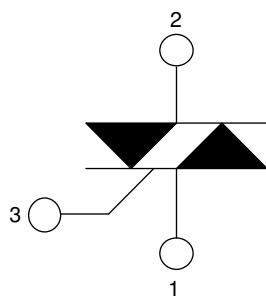
$V_{0\max}$  threshold voltage 0,86 V  
 $R_{0\max}$  slope resistance \* 10 mΩ

## Outlines TO-268AA (D3Pak-HV)



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.90	5.10	0.193	0.201
A1	2.70	2.90	0.106	0.114
A2	0.02	0.25	0.001	0.010
b	1.15	1.45	0.045	0.057
C	0.40	0.65	0.016	0.026
C2	1.45	1.60	0.057	0.063
D	13.80	14.00	0.543	0.551
D1	11.80	12.10	0.465	0.476
D2	7.50	7.80	0.295	0.307
D3	2.90	3.20	0.114	0.126
E	15.85	16.05	0.624	0.632
E1	13.30	13.60	0.524	0.535
e	5.450	BSC	0.215	BSC
H	18.70	19.10	0.736	0.752
L	1.70	2.00	0.067	0.079
L2	1.00	1.15	0.039	0.045
L3	0.250	BSC	0.010	BSC
L4	3.80	4.10	0.150	0.161

RECOMMENDED MINIMUM FOOT PRINT



## Thyristor

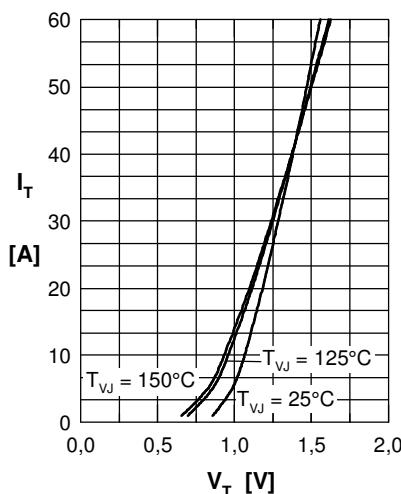


Fig. 1 Forward characteristics

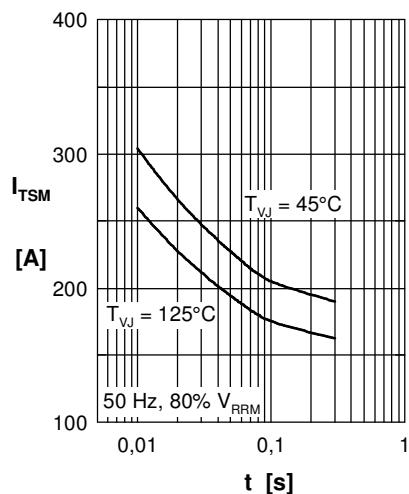
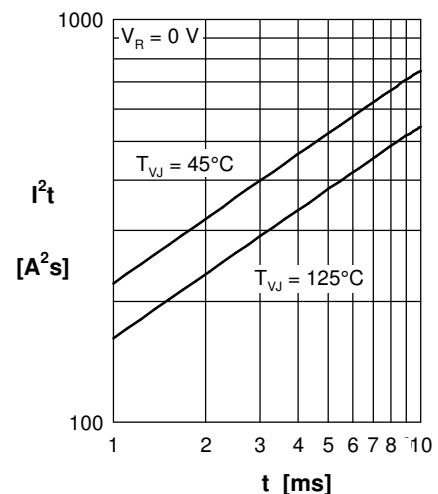
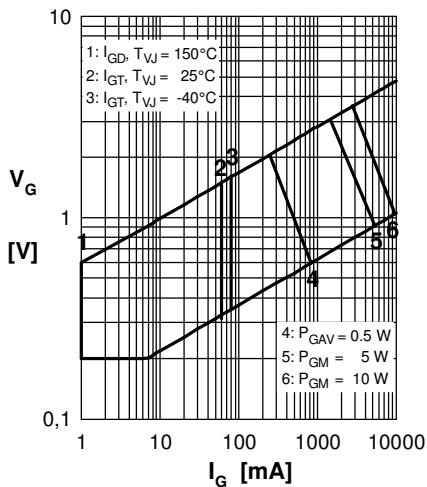
Fig. 2 Surge overload current  
 $I_{TSM}$ : crest value,  $t$ : durationFig. 3  $I^2t$  versus time (1-10 s)

Fig. 4 Gate voltage &amp; gate current

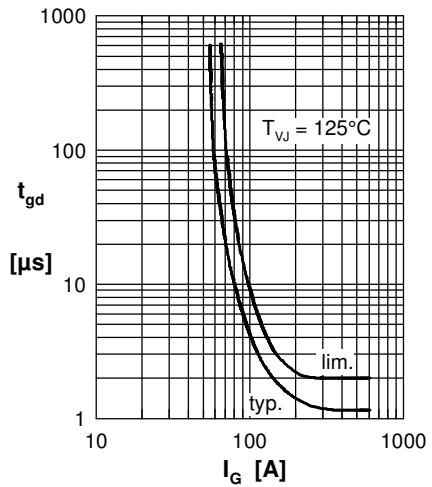
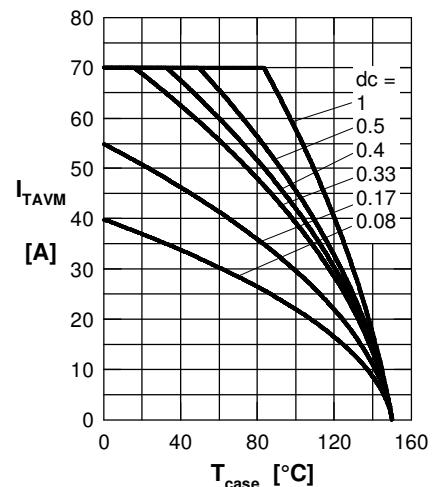
Fig. 5 Gate controlled delay time  $t_{gd}$ 

Fig. 6 Max. forward current at case temperature

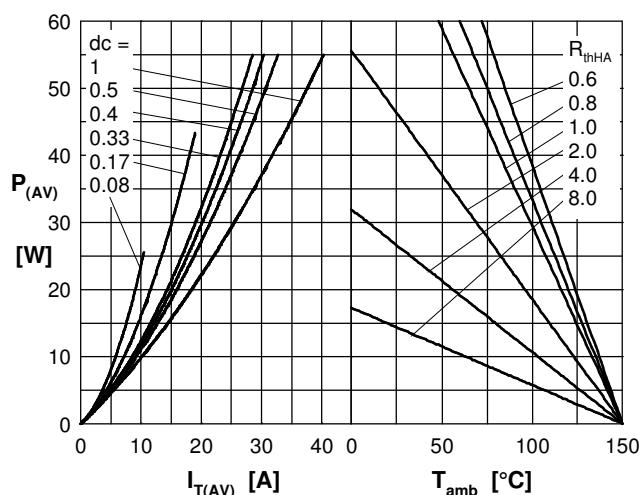
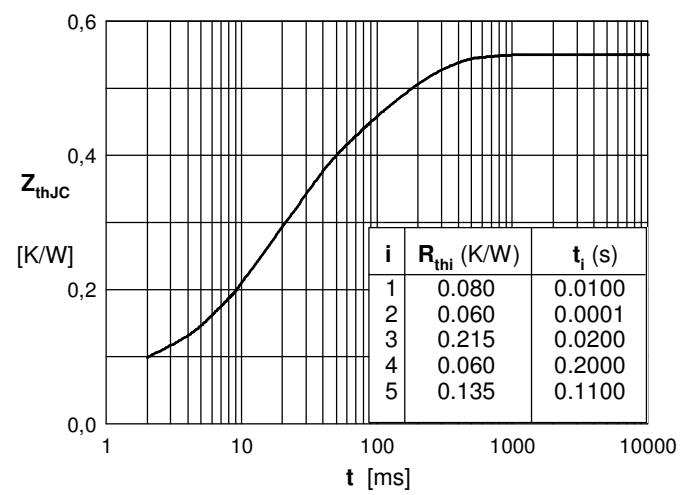
Fig. 7a Power dissipation versus direct output current  
Fig. 7b and ambient temperature

Fig. 7 Transient thermal impedance junction to case